Technical Data Sheet

SEOUL SEMICONDUCTOR

Specification
SPWW8F0E

SSC		Customer
Drawn	Approval	Approval

Rev. 0.00

March 2011.

www.Acrich.com

서식번호 : SSC- QP- 7- 07- 24 (Rev.00)

Technical Data Sheet

SEOUL SEMICONDUCTOR

SPWW8F0E

Rev. 0.00

March 2011.

www.Acrich.com

서식번호 : SSC- QP- 7- 07- 24 (Rev.00)

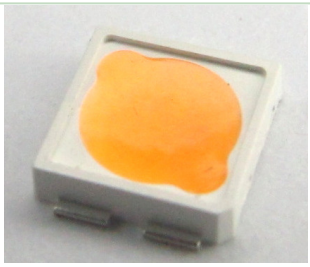
Technical Data Sheet

SEOUL SEMICONDUCTOR

SPWW8F0E

SPWW8F0E

1. Description



It has a substrate made up of a molded plastic reflector sitting on top of a bent lead frame (AG Plating).
The die is attached within the reflector cavity and the cavity is encapsulated by silicone
The high reliability feature is crucial to automotive front, Interior lamp and General Lights

Features

- Industry Standard SMT package
- Low thermal resistance
- Lead free product
- RoHS Compliant

Applications

- Lighting

Rev. 0.00
March 2011.
www.Acrich.com
서식번호 : SSC- QP- 7- 07- 24 (Rev.00)

2. Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power Dissipation[1]	P_d	1	W
Forward Current (Ta = 25℃)	I_F	100 (min.) 300 (typ.) 400 (max.)	mA
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +100	℃
Junction Temperature	T_j	125	℃
Thermal Resistance	R_{th-JS}	13	K/W

[1]. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.

3. Electro-Optical characteristics

(I_F=300mA)

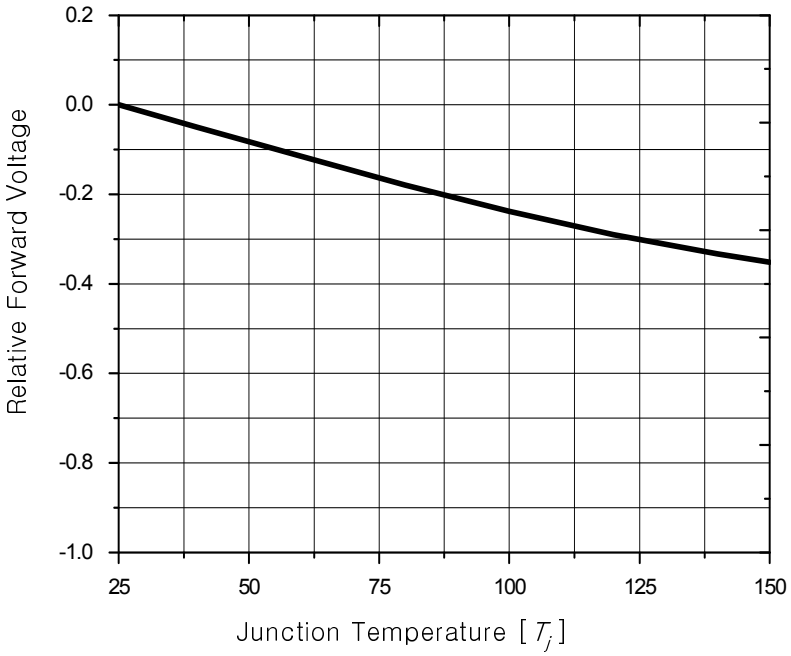
Parameter	Symbol	Min	Typ	Max	Unit
Forward Voltage	V_F	-	3.4	3.75	V
Luminance Flux [1]	Φ_V		95		lm
Correlated Color Temperature [2]	*CCT*		3000		K
CRI	R_a	80			-
Viewing Angle [3]	$2\theta_{1/2}$	120			deg.

[1]. The luminous Flux was measured at the peak of the spatial pattern which may not be aligned with the mechanical axis of the LED package. Luminous Flux Measurement allowance is ±10%
[2]. Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
Color coordinate : 0.005, CCT ± 5% tolerance
[3]. $2\theta_{\frac{1}{2}}$ is the off-axis where the luminous intensity is 1/2 of the peak intensity.

4. Characteristic Diagram

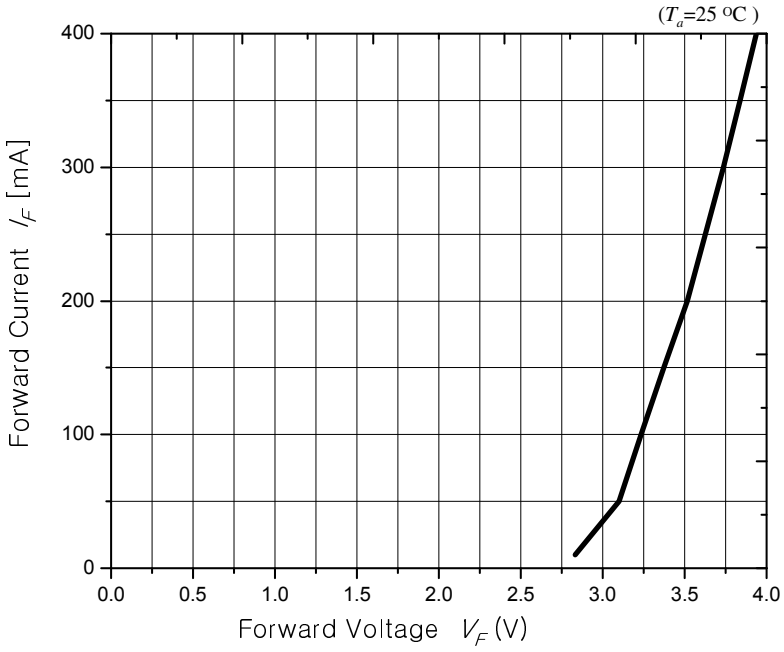
Wavelength vs. Relative Spectral Power Distribution

(I_F=300mA)

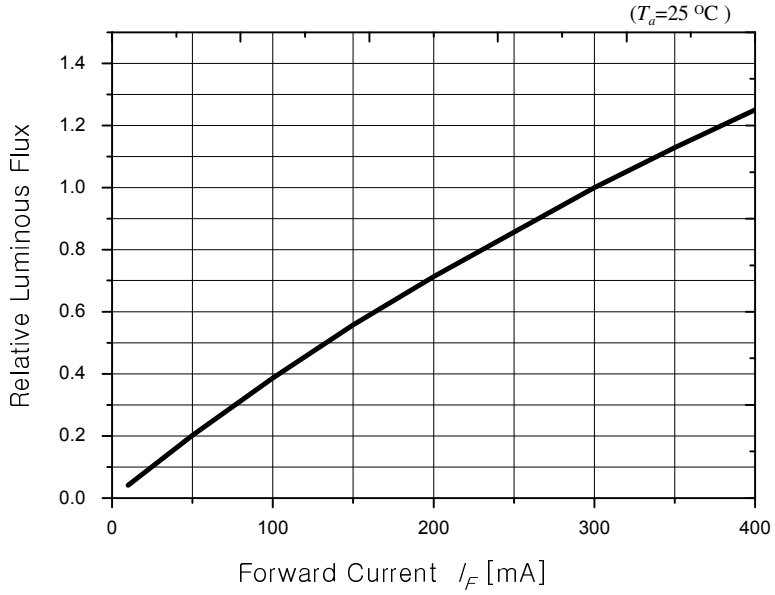


4. Characteristic Diagram

Forward Current vs. Forward Voltage



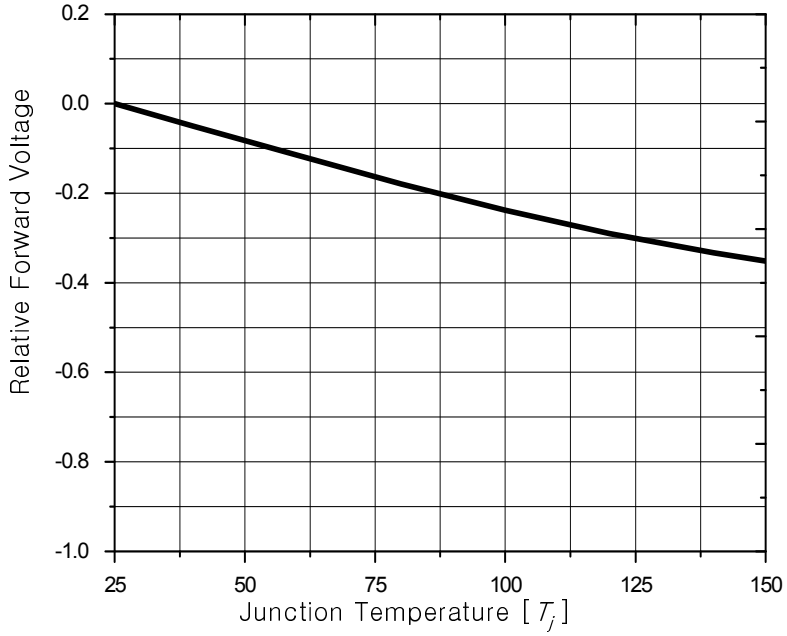
Relative Luminous Intensity vs Forward Current



4. Characteristic Diagram

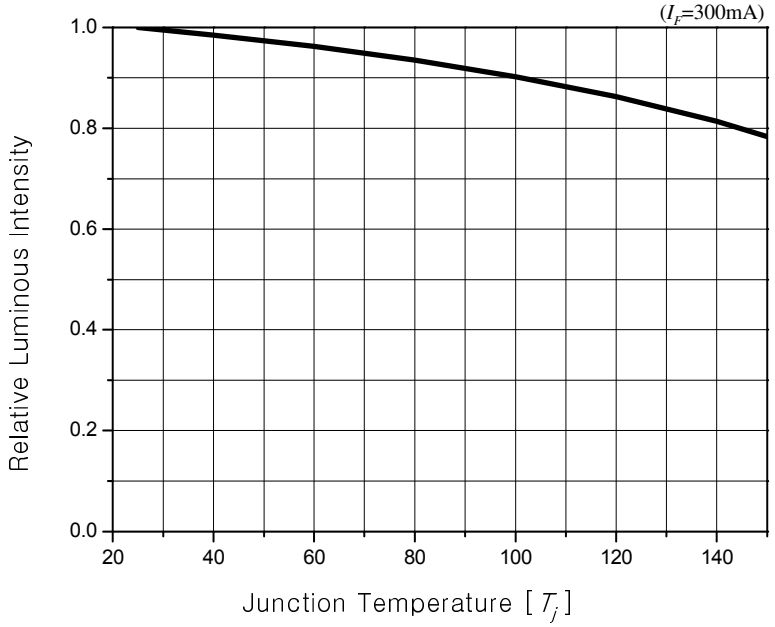
Relative Forward Voltage vs. Junction Temperature

(I_F=300mA)



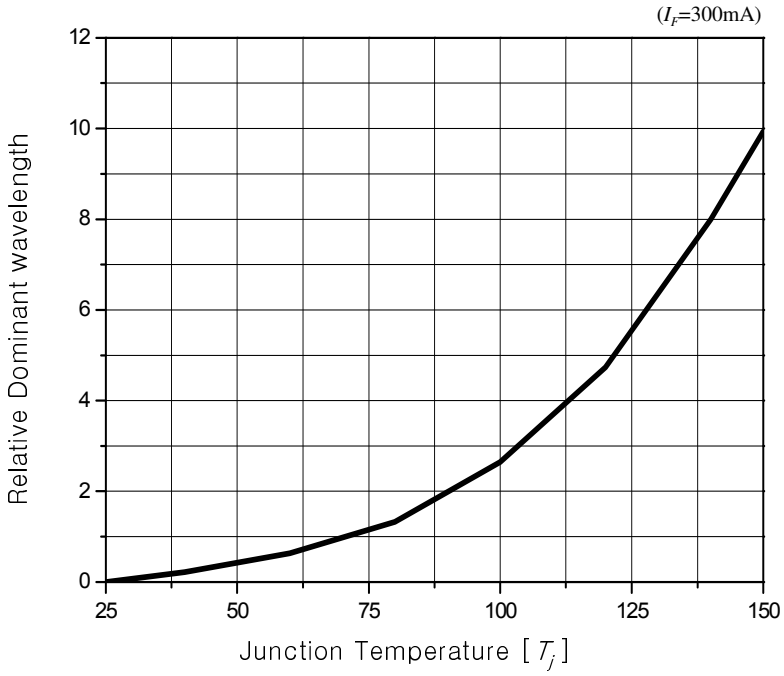
Relative Luminous Intensity vs. Junction Temperature

(I_F=300mA)



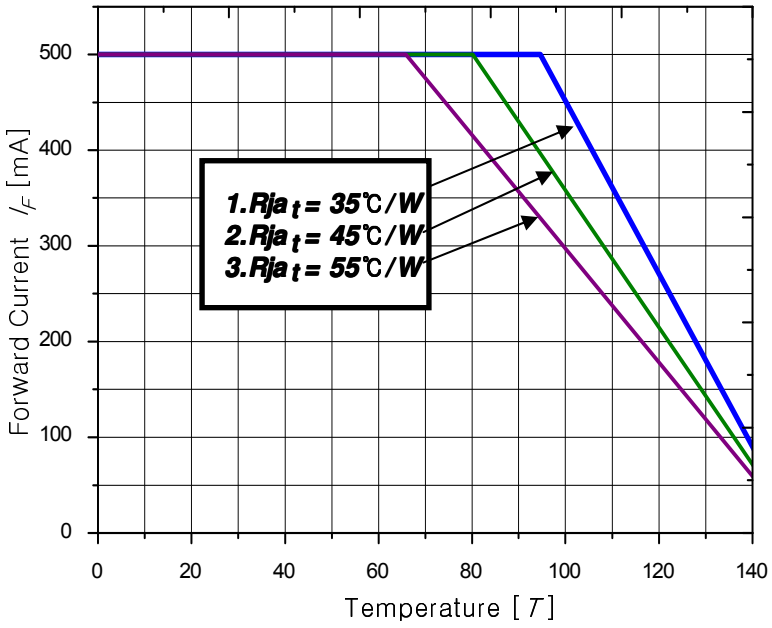
4. Characteristic Diagram

Relative Dominant Wavelength vs. Junction Temperature

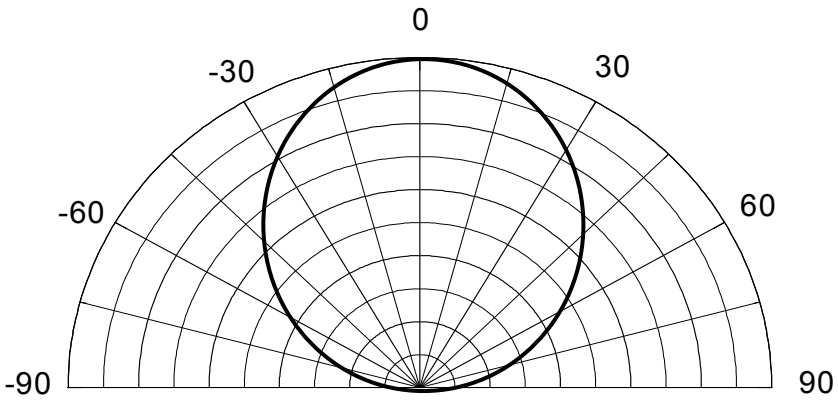


4. Characteristic Diagram

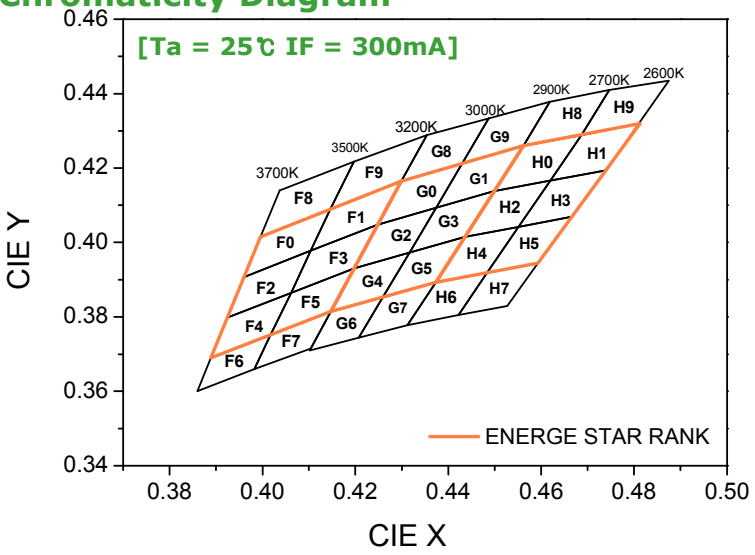
Ambient Temperature vs. Forward Current



Radiation Diagram



5. CIE Chromaticity Diagram



F0		F1		F2		F3		F4	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.3996	0.4015	0.4146	0.4089	0.396	0.3907	0.4104	0.3978	0.3925	0.3798
0.396	0.3907	0.4104	0.3978	0.3925	0.3798	0.4062	0.3865	0.3889	0.369
0.4104	0.3978	0.4248	0.4048	0.4062	0.3865	0.4198	0.3931	0.4017	0.3751
0.4146	0.4089	0.4299	0.4165	0.4104	0.3978	0.4248	0.4048	0.4062	0.3865

F5		F6		F7		F8		F9	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.4062	0.3865	0.3889	0.369	0.4017	0.3751	0.4037	0.414	0.4197	0.4217
0.4017	0.3751	0.386	0.36	0.3983	0.366	0.3996	0.4015	0.4146	0.4089
0.4147	0.3814	0.3983	0.366	0.4104	0.3715	0.4146	0.4089	0.4299	0.4165
0.4198	0.3931	0.4017	0.3751	0.4147	0.3814	0.4197	0.4217	0.4354	0.4288

G0		G1		G2		G3		G4	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.4299	0.4165	0.443	0.4212	0.4248	0.4048	0.4374	0.4093	0.4198	0.3931
0.4248	0.4048	0.4374	0.4093	0.4198	0.3931	0.4317	0.3973	0.4147	0.3814
0.4374	0.4093	0.4499	0.4138	0.4317	0.3973	0.4436	0.4015	0.4259	0.3853
0.443	0.4212	0.4562	0.426	0.4374	0.4093	0.4499	0.4138	0.4317	0.3973

G5		G6		G7		G8		G9	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.4317	0.3973	0.4147	0.3814	0.4259	0.3853	0.4354	0.4288	0.4487	0.4333
0.4259	0.3853	0.4102	0.371	0.4207	0.3744	0.4299	0.4165	0.443	0.4212
0.4373	0.3893	0.4207	0.3744	0.4312	0.3778	0.443	0.4212	0.4562	0.426
0.4436	0.4015	0.4259	0.3853	0.4373	0.3893	0.4487	0.4333	0.4619	0.4378

H0		H1		H2		H3		H4	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.4562	0.426	0.4687	0.4289	0.4499	0.4138	0.462	0.4166	0.4436	0.4015
0.4499	0.4138	0.462	0.4166	0.4436	0.4015	0.4551	0.4042	0.4373	0.3893
0.462	0.4166	0.474	0.4194	0.4551	0.4042	0.4666	0.4069	0.4483	0.3919
0.4687	0.4289	0.481	0.4319	0.462	0.4166	0.474	0.4194	0.4551	0.4042

H5		H6		H7		H8		H9	
CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y	CIE X	CIE Y
0.4551	0.4042	0.4373	0.3893	0.4483	0.3919	0.4619	0.4378	0.4747	0.441
0.4483	0.3919	0.4312	0.3778	0.4422	0.3805	0.4562	0.426	0.4687	0.4289
0.4593	0.3944	0.4422	0.3805	0.4527	0.383	0.4687	0.4289	0.481	0.4319
0.4666	0.4069	0.4483	0.3919	0.4593	0.3944	0.4747	0.441	0.4875	0.4435

6. Binning Table

Bin Code		
Luminous Flux (lm) @ I_F = 300mA	Color Chromaticity Coordinate @ I_F = 300mA	Forward Voltage (V) @ I_F = 300mA

Luminous Flux (lm) @ I_F = 300mA

Bin Code	Min.	Max.
T2	80	91
U1	91	100
U2	100	109
U3	109	118

Color Chromaticity Coordinate @ I_F = 300mA

Bin Code	Min.	Max.
Ref. 10 pages		

Forward Voltage (V) @ I_F = 300mA

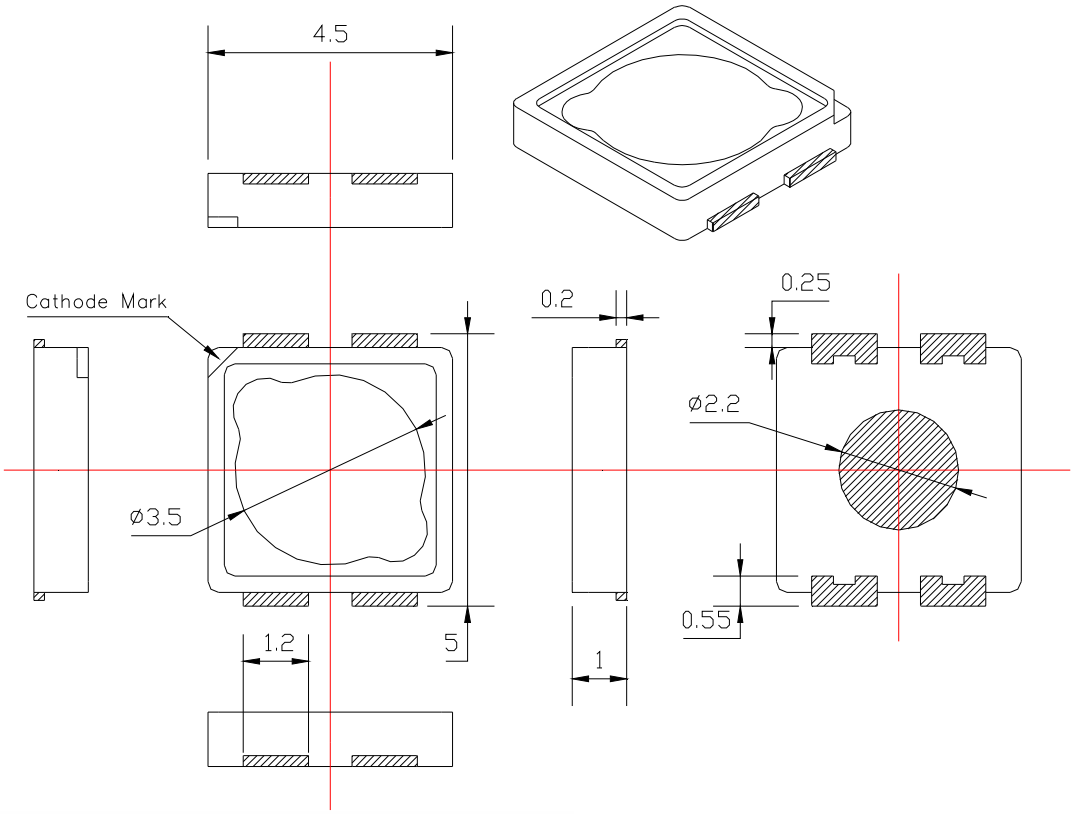
Bin Code	Min.	Max.
H	3.0	3.25
I	3.25	3.50
J	3.50	3.75

☐ Available ranks

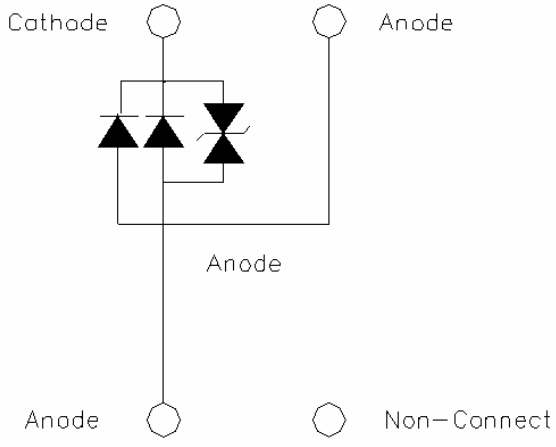
7. outline dimension

< Package Outline >

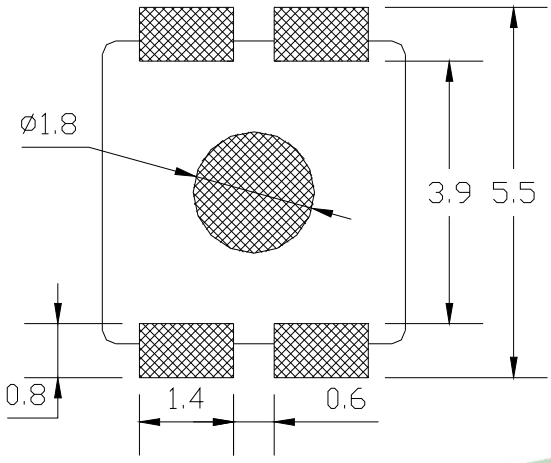
(Tolerance: ±0.2, Unit: mm)



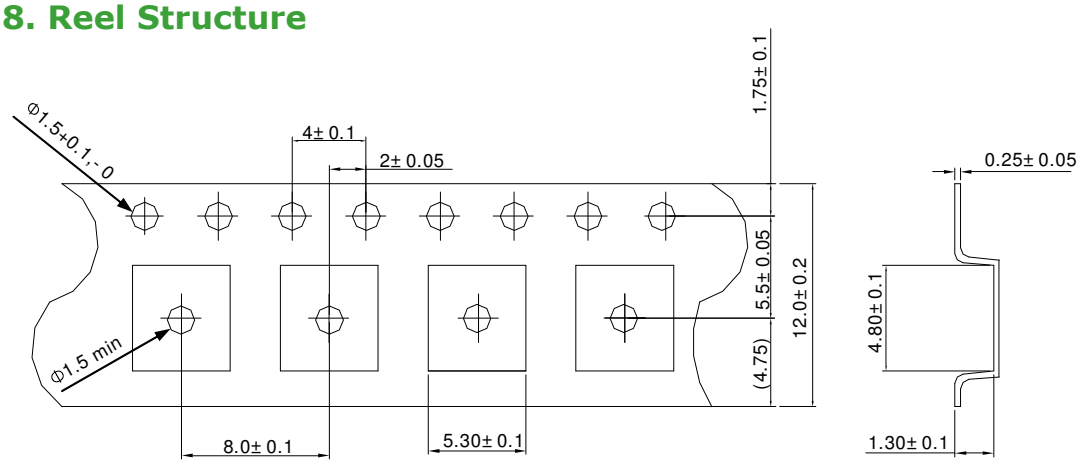
< CirCuit Diagram >

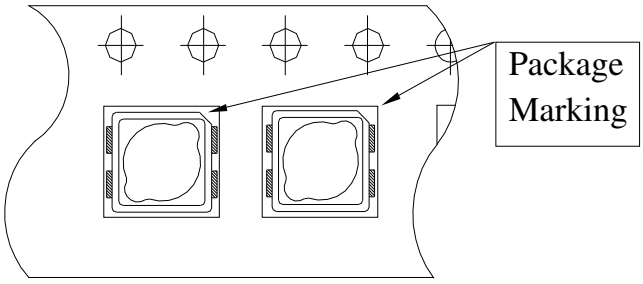


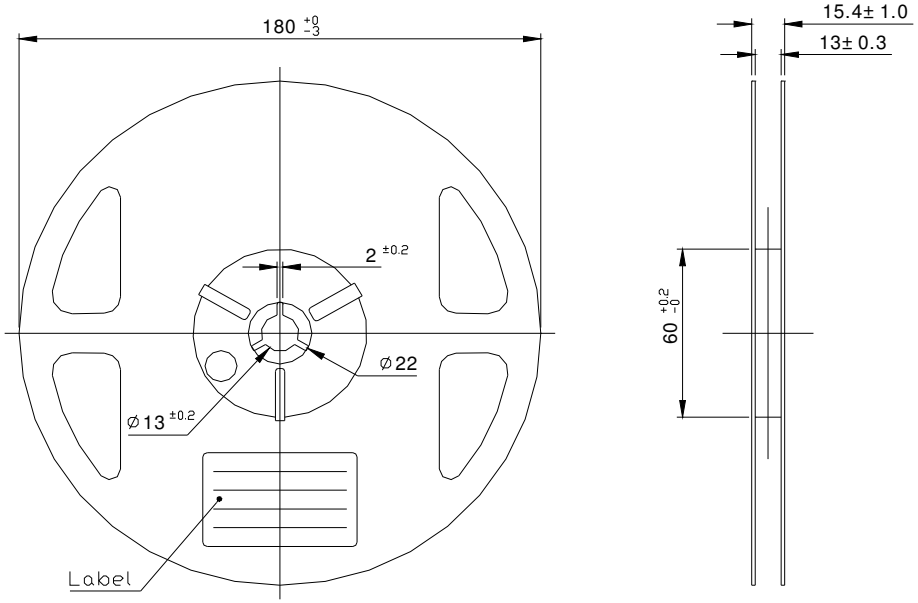
< Solder Pattern >



8. Reel Structure



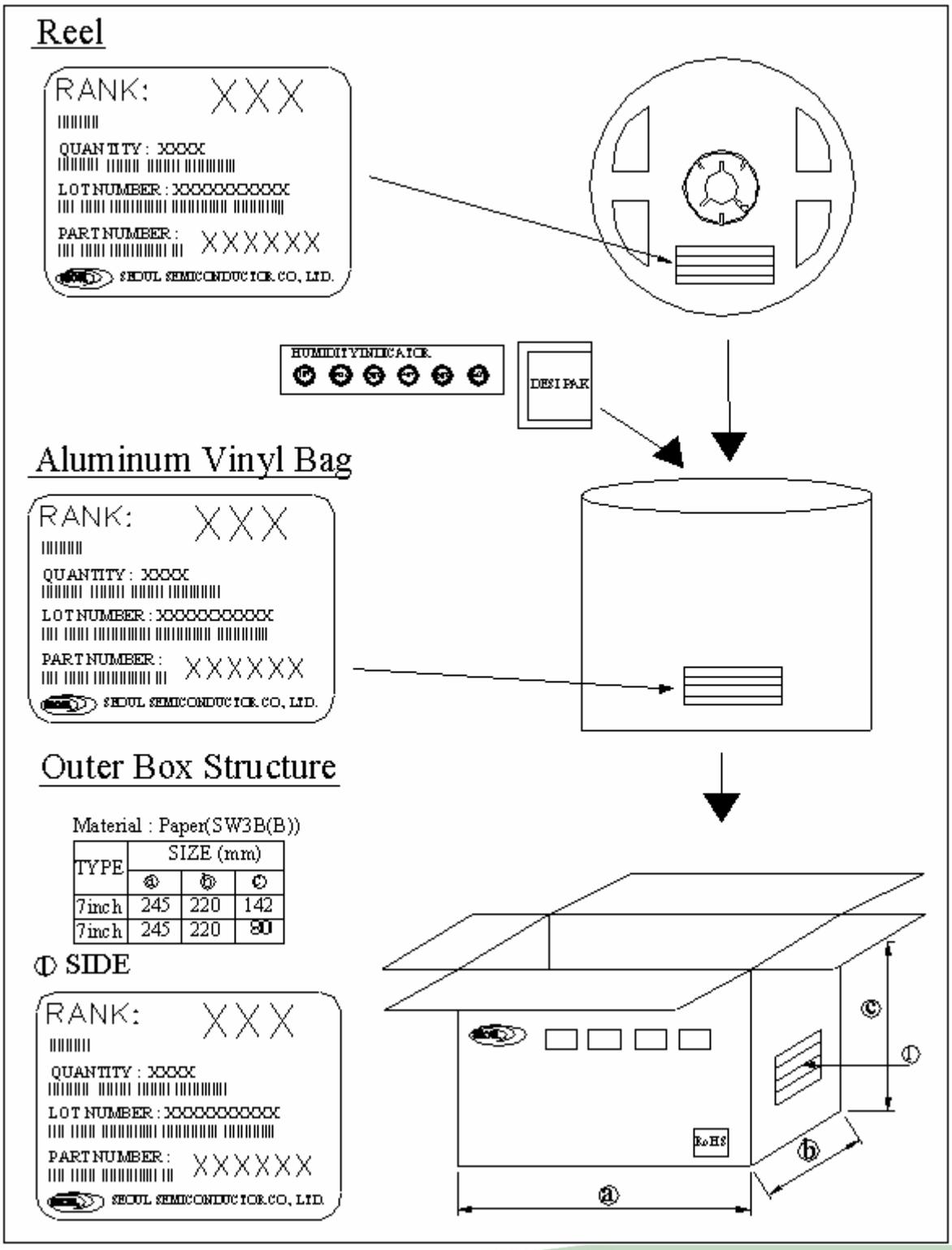




(Tolerance: ±0.2, Unit: mm)

(1) Quantity : 1,500pcs/Reel
(2) Cumulative Tolerance : Cumulative Tolerance/10 pitches to be ± 0.2mm
(3) Adhesion Strength of Cover Tape : Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10º to the carrier tape
(4) Package : P/N, Manufacturing data Code No. and quantity to be indicated on a damp proof Package

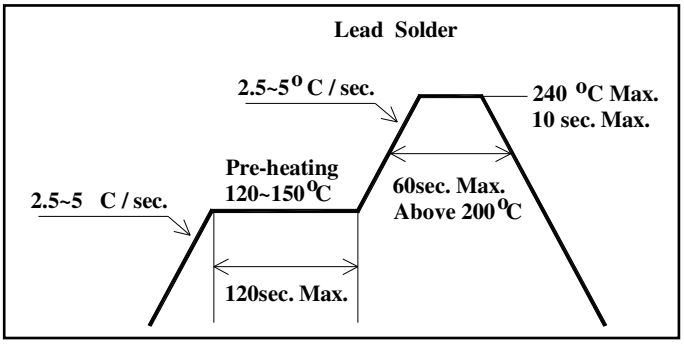
9. Packing


Reel
RANK: XXX
QUANTITY : XXXX
LOT NUMBER : XXXXXXXXXX
PART NUMBER : XXXXXX
SEOUL SEMICONDUCTOR CO., LTD.
HUMIDITY INDICATOR
DESI PAK
Aluminum Vinyl Bag
RANK: XXX
QUANTITY : XXXX
LOT NUMBER : XXXXXXXXXX
PART NUMBER : XXXXXX
SEOUL SEMICONDUCTOR CO., LTD.
Outer Box Structure
Material : Paper(SW3B(B))
TYPE
SIZE (mm)
ⓐ
ⓑ
ⓒ
7inch 245 220 142
7inch 245 220 80
① SIDE
RANK: XXX
QUANTITY : XXXX
LOT NUMBER : XXXXXXXXXX
PART NUMBER : XXXXXX
SEOUL SEMICONDUCTOR CO., LTD.
RoHS
ⓒ
①
ⓑ
ⓐ

10. Soldering

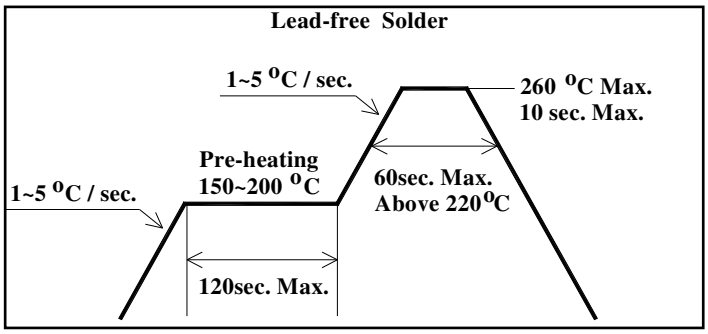
(1) Lead Solder

Lead Solder	
Pre-heat	120~150℃
Pre-heat time	120 sec. Max.
Peak-Temperature	240℃ Max.
Soldering time Condition	10 sec. Max.



(2) Lead-Free Solder

Lead Free Solder	
Pre-heat	150~200℃
Pre-heat time	120 sec. Max.
Peak-Temperature	260℃ Max.
Soldering time Condition	10 sec. Max.



(3) Hand Soldering conditions

Do not exceed 4 seconds at maximum 315°C under soldering iron.

(4) The encapsulated material of the LEDs is silicone.

Precautions should be taken to avoid the strong pressure on the encapsulated part.

So when using the chip mounter, the picking up nozzle that does not affect the silicone resign should be used.

Note : In case that the soldered products are reused in soldering process, we don't guarantee the products.

11. precaution for use

(1) Storage

In order to avoid the absorption of moisture, it is recommended to store in a dry box with a desiccant. Otherwise, to store them in the following environment is recommended.
Temperature : 5ºC ~30ºC Humidity : maximum 70%RH

(2) Attention after open.

LED is correspond to SMD, when LED be soldered dip, interfacial separation may affect the light transmission efficiency, causing the light intensity to drop. Attention in followed; Keeping of a fraction
Temperature : 5 ~ 40ºC Humidity : less than 10%

(3) In the case of more than 4 week passed after opening or change color of indicator on desiccant, components shall be dried 10-12hr. at 60± 5ºC.

(4) Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.

(5) Quick cooling shall be avoided.

(6) Components shall not be mounted on warped direction of PCB.

(7) Anti radioactive ray design is not considered for the products.

(8) This device should not be used in any type of fluid such as water, oil, organic solvent etc. When washing is required, IPA should be used.

(9) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.

(10) The LEDs must be soldered within seven days after opening the moisture-proof packing.

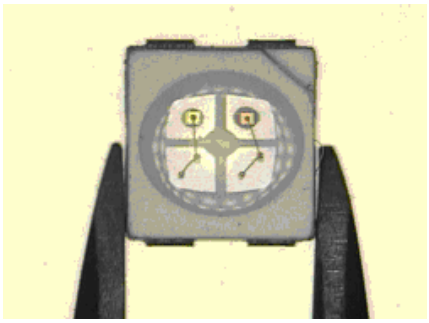
(11) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.

(12) The appearance and specifications of the product may be modified for improvement without notice.

12. Handling of Silicone Resin LEDs

(1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.

(2) In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.



(3) When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented.
This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

(4) Silicone differs from materials conventionally used for the manufacturing of LEDs. These conditions must be considered during the handling of such devices. Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust.
As mentioned previously, the increased sensitivity to dust requires special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components.

(5) SSC suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin.
Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.